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**PATENT NUMBER and
ISSUE DATE**

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS 251	SUBCLASS 771	GAU 2827	EXAMINER ZARNEKE
**APPLICANTS					

****APPLICANTS:** Honda Hirokazu

****CONTINUING DATA VERIFIED:**
THIS APPLICATION IS A DIV OF 09/712,105 11/14/2000

**** FOREIGN APPLICATIONS VERIFIED:**
JAPAN 325770/1999 11/16/1999

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no
ATTORNEY DOCKET NO NEC 00USFP553 DIV		
TITLE : Semiconductor device and manufacturing method the same		

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED		
			Total Claims	Print Claim for O.G.	
ISSUE FEE		DRAWING			
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.	Print Fig.	
		Primary Examiner			
		PREPARED FOR ISSUE		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

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